

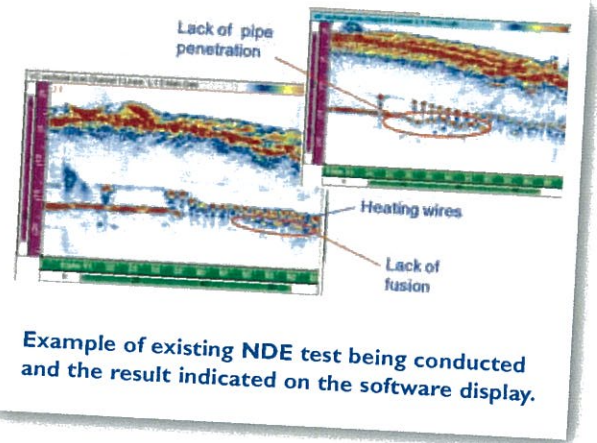
Now for something completely different!

Monitoring Quality in Plastic Pipes – SMART EU Project

TestPEP has been running successfully for twelve months, the goal is the development and validation of an automatic non-destructive testing of welded joints in plastic pipes.

SMART Group's role in the project, like our other EU activity, is to disseminate information on the project and provide training. A further activity is to take the equipment and, using inspection criteria produced from mechanical testing, confirm the test equipment can detect joint failure that does reduce the life of the welds. A highlight for the author is to test welds in deep muddy ditches, half full of water and test the robustness of the equipment.

Although this application of non-destructive testing is a little different from SMART's normal activity the testing methodology, use of electronic, setting and training inspection staff is what we do well. The EU FP7 funded project involves 13 organisations from seven European countries.



Example of existing NDE test being conducted and the result indicated on the software display.

Further information on the project and some of the results are available at www.testpep.eu SMART Group will be holding a webinar on the subject in the next few months, further details at www.smartgroup.org/diary

The TestPEP project is managed by TWI and has received funding from the European Community's Seventh Framework Programme managed by REA-Research Executive Agency (FP7-SME-2008-2) under grant agreement no. 243791.

Do YOU have a technical question? Let *smart-e-link* help!

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As examples, two recent questions prompted excellent debate and comment:

1. Ioan Tempea, Ing Ingenieur Principal de Fabrication/ Senior Manufacturing Engineer, Digico Electronics Manufacturing, posed the question: "I need to know how package on package is assembled in real life. I attended Bob Willis' course and found it very good, it's just that neither our Mydata or Fujii IP3 machines are able to handle the process (pick-dip-place)."

So how are you doing it? What insertion machines can handle the process and if you do it automatic-manual manner; how do you go about it?

2. Mike Fenner, Indium and SMART Group Committee Member asked: "Here's a piece of string question! What percentage - a range would do - would you guess/estimate of modern PCB area is solder pads? I was asked this and said 10 - 15% maybe 20% without a second's thought, then put the phone down. Now I realise I don't really know, but rather think I ought to. Also that someone has measured it from their Gerber or something. If not I'll take an average number from this group. That is probably as good as it will ever be."

These questions prompted much comment, thanks to all who participated *smart-e-link* is archived on our web site www.smartgroup.org